This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

**PCN Title:** Certification of STATSPchipPAC Shanghai, China and AMKOR Philippines as additional sources for Assembly & Test of QFP Packages

**Publication Date:** 05-Jan-2009

**Samples Available Date:** 18-Dec-2008 (the earliest date that a customer could expect to receive changed material)

**Effectivity Date:**

**Description Of Change**

ADI is certifying STATSPchipPAC Shanghai, China and AMKOR Philippines for Assembly & Test of QFP packages. STATSPchipPAC China will be a new manufacturing site for ADI. AMKOR Philippines has been a long standing ADI manufacturing site for package types such as SO, BGA and LF CSP.

- Added devices which were not listed in Rev C. See attached detail/parts list.
- Lead bearing parts had highlighted as “None” because Sn/Pb plating option will be discontinued.
- Lead bearing parts will continue to available until Dec 2008.

**Timing:**

Over the course of 2008 ADI will be qualifying multiple LQFP leadcounts and body sizes at both STATSPchipPAC China and AMKOR Philippines. Parts assembled in the 7x7 LQFP package are being transferred first. The Assembly process will transfer first. Details on any Test transfers will follow in subsequent PCNS. First shipment of 7x7 LQFP products to customers will be no earlier than June 2008.

- Updated time line, Transfer location and Test location based on new inputs

**Details:**

- Device quality, function, and performance, as specified by Product Data Sheets, will be unaffected by this change.
- No change in the Fit or Function of the QFP packages Assembled and Tested.
- The form - top mark - will change from ink to laser mark on those QFP packages presently marked with ink top mark.
- Changes to molding compound and die attach material will be made to consolidate on “Green Materials (Already Qualified and High volume running BOM in ADI)” as required by the majority of our customer base in the near future.
- Sn/Pb plating will be converted to ROHS compliant Sn plating.
- All changes yellow color coded in the detail/parts list.

Specific change details for products in 7x7 QFP packages are included in the attached detail/parts list file. Update products in 14x20 MQFP & 20x20 LQFP packages also included in the attached detail/parts list file.

All products in 7x7 ~ 28x28 LQFP, 10x10 ~ 28x28 MQFP and 7x7 ~ 14x14 TQFP packages are included in the attached parts list files.

**Reason For Change**

ADI is committed to ensuring the necessary manufacturing capability and capacity to meet our customer requirements. This certification enables ADI to meet our customers' requirements for a reliable supply chain of QFP packages.

STATSPCHIPPAC SINGAPORE will discontinue production support of QFP on March 31st 2009.

**Impact of the change (positive or negative) on fit, form, function & reliability**

Device quality, function, and performance, as specified by Product Data Sheets, will be unaffected by this change.

**Summary of Supporting Information**

Multiple Qualifications have been successfully completed per Analog Devices specification ADI012, Procedure for Qualification of New or Revised Processes or Products. A Summary of Qualification Results and Plans is provided with this PCN.

Any special requests should be identified within the first 30 days of this PCN.

7x7 LQFP: First shipment to customers no earlier than June 2008.

Preliminary dates for transfer for the other package types are shown in the attached XL files. These are subject to change and will be updated in subsequent PCN revisions.

**Supporting Documents**

- **Attachment 1:** ADI_PCN_07_0077_Rev_D_QFP Transfer Qualification Results-tests_DEC12CL.doc
- **Attachment 2:** ADI_PCN_07_0077_Rev_D_07_0077Rev_D_LQFP_Dec17.xls
- **Attachment 3:** ADI_PCN_07_0077_Rev_D_07_0077Rev_D_MQFP_Dec15.xls
- **Attachment 4:** ADI_PCN_07_0077_Rev_D_07_0077Rev_D_TQFP_Dec15.xls
- **Attachment 5:** ADI_PCN_07_0077_Rev_D_07_0077Rev_D_Obsolescence_Dec15.xls
For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative

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## Appendix B - Revision History

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<th>Rev Description</th>
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<td>12-Nov-2007</td>
<td>Initial Release</td>
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<tr>
<td>Rev. B</td>
<td>27-Jun-2008</td>
<td>Rev B: Update products in 14x20 MQFP &amp; 20x20 LQFP packages. Revised Die attach epoxy. Standardize on 8361JJ and 3230. Updated time line Transfer location and Test location based on new inputs. For those lead bearing parts highlighted as 'None' the Sn/Pb option will be discontinued. For these devices the lead bearing device will continue to be available until Dec 2008. Added devices which were not listed in rev. A. All changes yellow color coded in the detail/parts list.</td>
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<td>Rev. C</td>
<td>26-Aug-2008</td>
<td>Rev C: Updated to clarify time line detail parts lists and correct typo on qual data_1 report. No new parts are added at this revision.</td>
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<td>Rev. D</td>
<td>05-Jan-2009</td>
<td>Update Qual results and plans of all products in 7x7<del>28x28 LQFP, 10x10</del>28x28 MQFP and 7x7~14x14 TQFP. Added devices which were not listed in Rev. C, report provided. Indicate all obsolete devices, list provided. Updated Test location because Test hardware and platform transfer plan changed.</td>
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